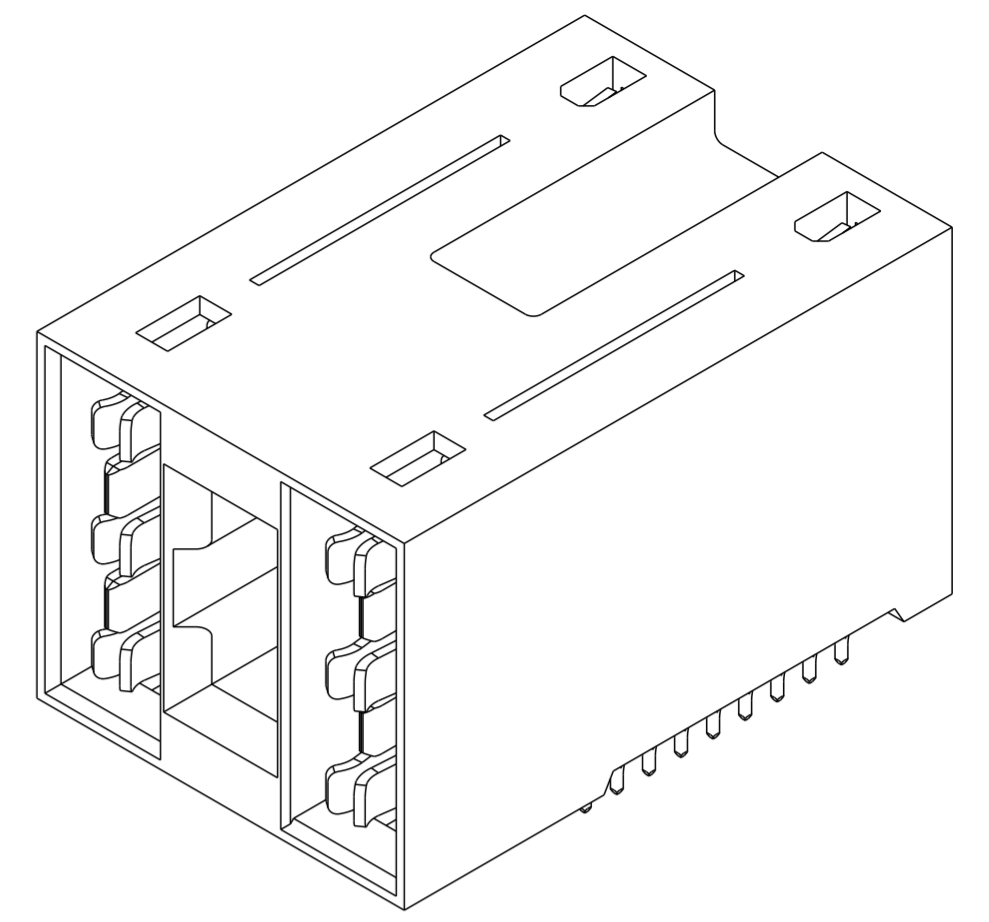
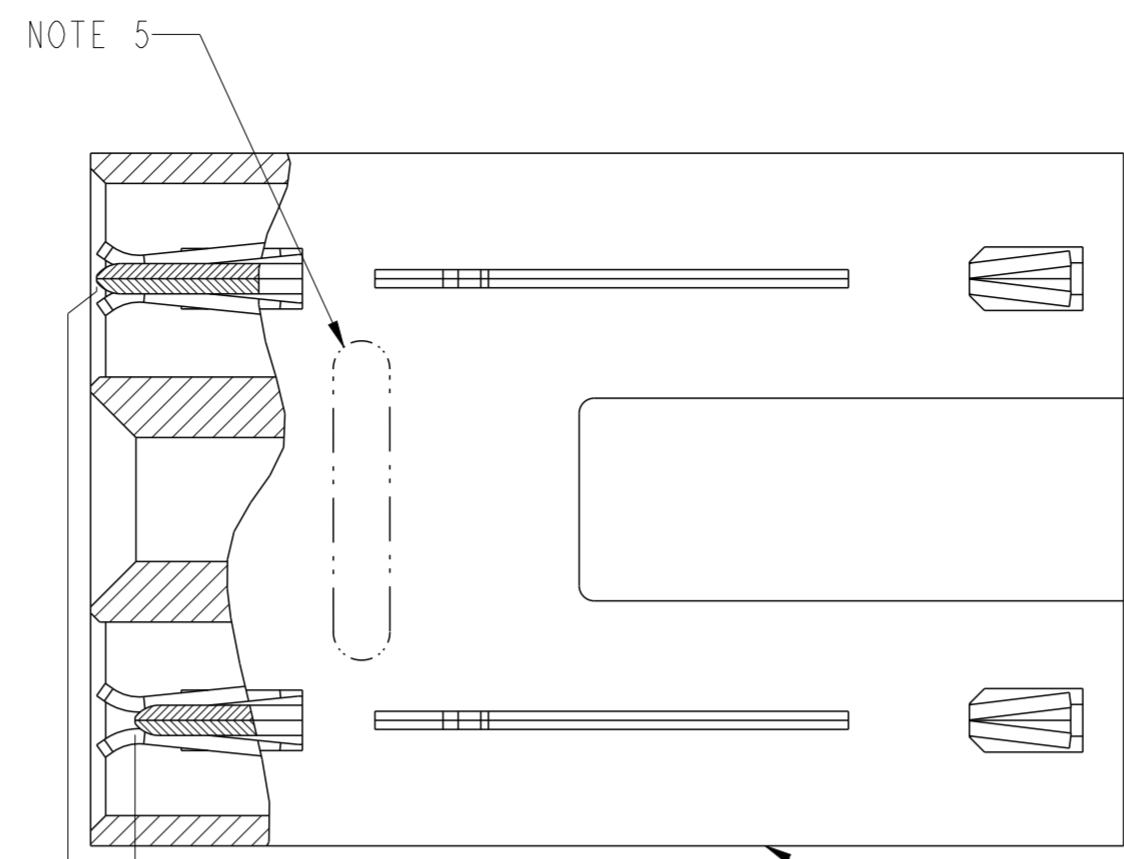


PART NUMBER	FIRST MATE (LONG) CONTACT POSN	SECOND MATE (SHORT) CONTACT POSN	TAIL TYPE
10087937-001LF	NONE	POSN 1 & 2	PRESS-FIT
10087937-002LF	POSN 1	POSN 2	

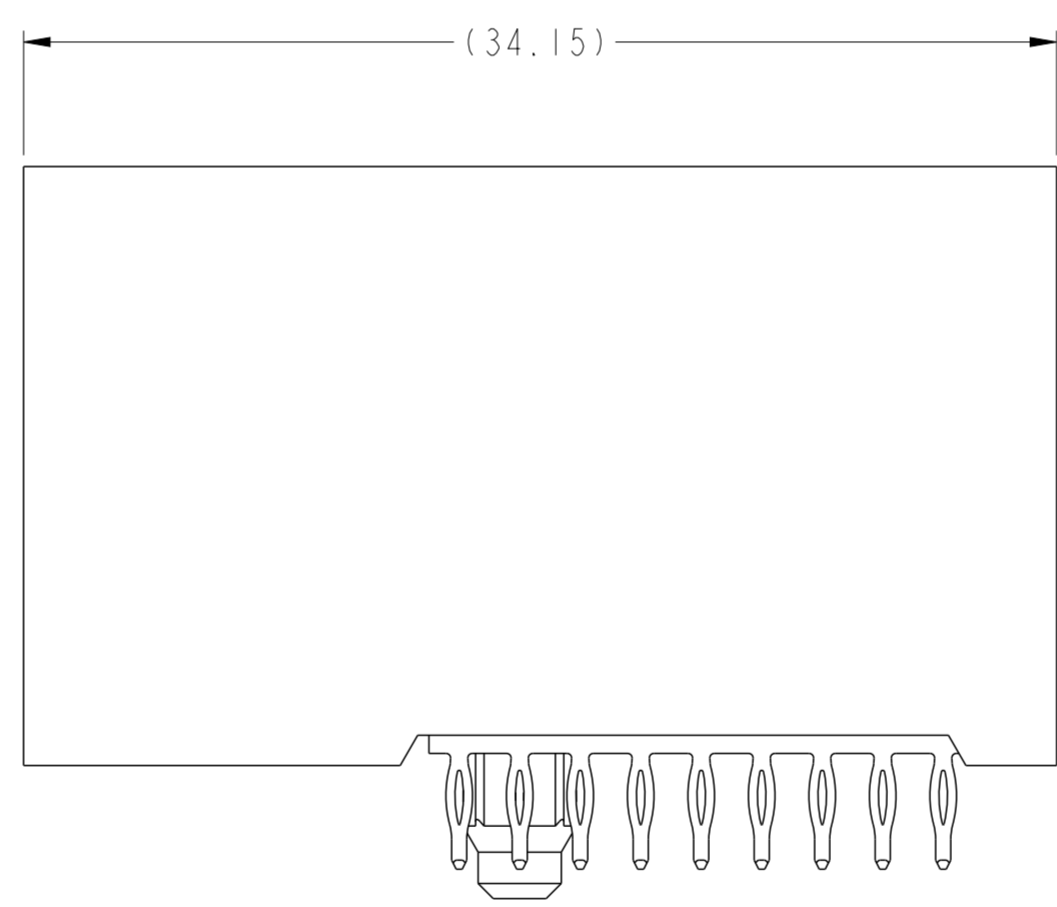
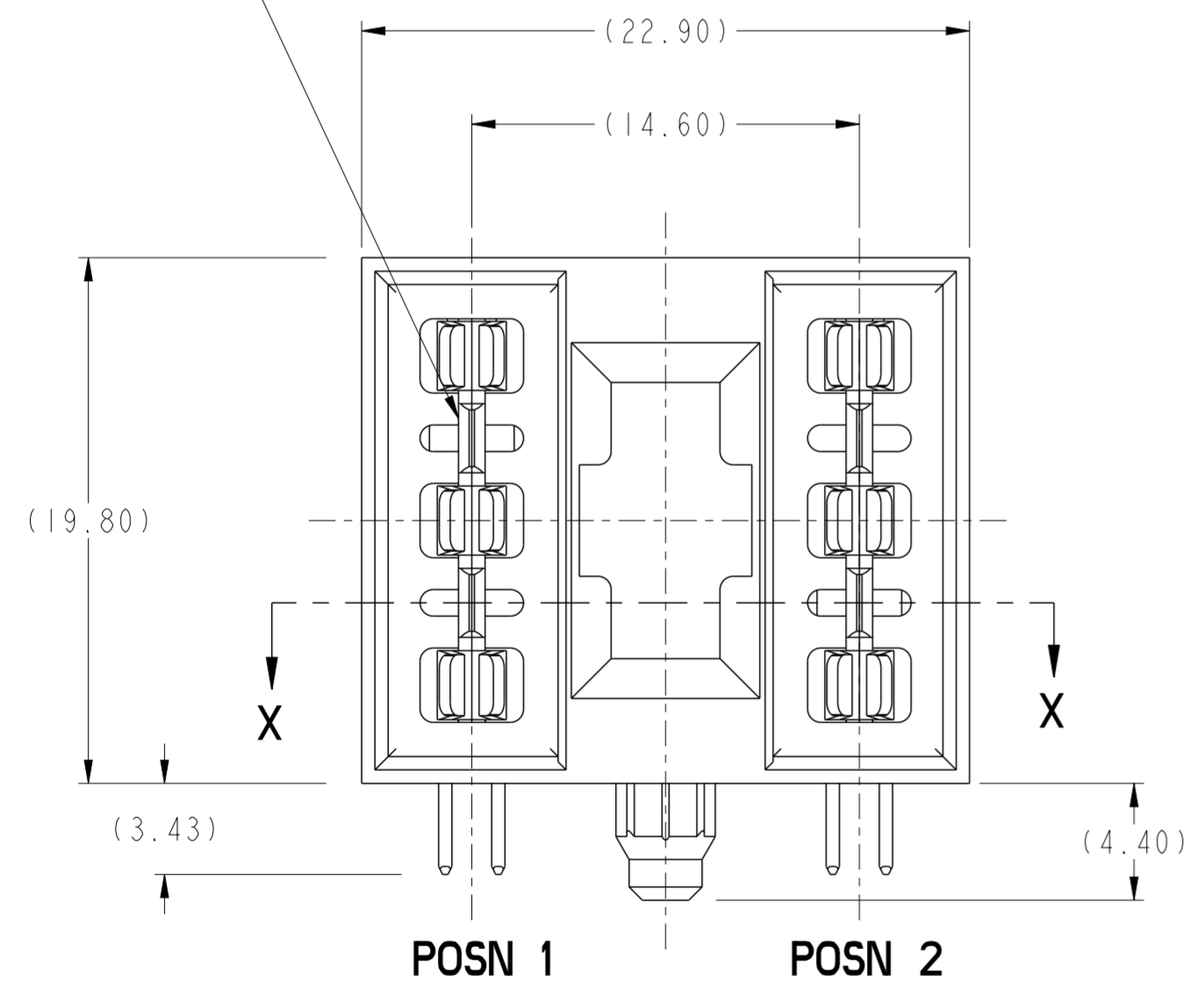


POWER CONTACTS,
LONG AND SHORT BLADES
(SEE DETAIL C)

(1.27)
CONTACT SEQUENCING

HOUSING
NOTE 8

SECTION X-X



KEYING FOR
LONG CONTACTS

KEYING FOR
SHORT CONTACTS

10087937-002 SHOWN

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spec ref	-	dr	NotFound DuWa	2010/04/28	projection	MM	size	A2	scale	4:1	
tolerance std	ASME Y14.5	eng	De-Ming Lu	2014/12/28			ecn no	ELX-DG-19849-1			
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	appr			Pei-Ming Zheng	2014/12/29	product family	HCI	rel level
surface	ASME Y14.5	linear	0.X	±0.5	0.XX	±0.25	0.XXX	±0.10	angular	0°	±2°
www.fci.com		title	ASSEMBLY, HEADER, R/A 2 POSN BACKPANEL MODULE W/GUIDE			cat. no.	-	Product - Customer Drw	sheet 1 of 2	rev	C

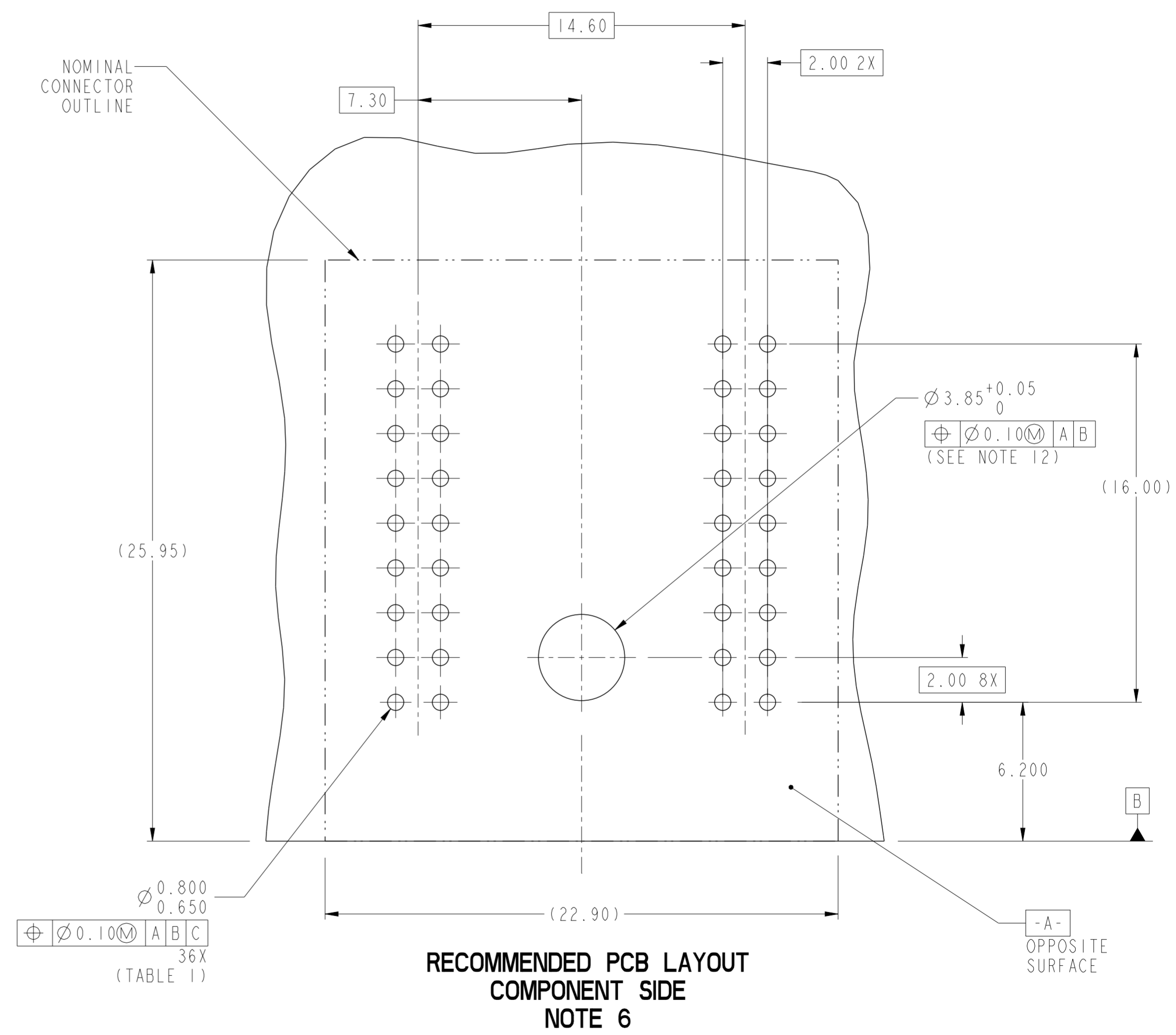
PDS: Rev :C

STATUS:Released

Printed: Dec 30, 2014

TOP LAYER DESCRIPTION	TABLE 1 (HCI POWER) PLATED THROUGH-HOLE REQUIREMENTS							
	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER
TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	--	--	--	0.65 - 0.80
IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	0.9 - 1.5um	--	0.70 - 0.80
IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	0.15 - 0.65um	0.70 - 0.80
COPPER (SEE NOTE 9)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	--	0.70 - 0.80
GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.003 - 0.007	FLASH UP TO 0.0002	--	--	0.69 - 0.80

- NOTES:
- CONNECTOR MATERIALS:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK
UL 94V-0 COMPLIANT
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
 - CONTACT FINISH (Ref. GS-12-380 SECTION 5.2)
 - PRODUCT SPECIFICATION: GS-12-380. (IN PROGRESS)
 - APPLICATION SPECIFICATION: GS-20-070. (IN PROGRESS)
 - PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
 - MINIMUM NOMINAL PCB THICKNESS: 1.6mm
 - PACKAGING MEETS FCI SPECIFICATION GS-14-1194
 - HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
 - COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
 - ALL HOLE SIZES ARE FINISHED HOLE SIZES UNLESS OTHERWISE NOTED.
 - THE GUIDANCE SYSTEM OF THIS PRODUCT IS "NOT" INTENDED TO BE USED AS AN OVERALL SYSTEM GUIDE.
 - UNPLATED HOLES.



RECOMMENDED PCB LAYOUT
COMPONENT SIDE
NOTE 6

dr	NotFound DuWa	2010/04/28	projection	MM	size	A2	scale	6:1
eng	De-Ming Lu	2014/12/28			ecn no	ELX-DG-19849-1	rel level	Released
chr	-	-						
appr	Pai-Ming Zheng	2014/12/29	product family	-	rel level	-	rel level	Released
		title ASSEMBLY, HEADER, R/A 2 POSN BACKPANEL MODULE W/GUIDE		dwg no 10087937	rev C		www.fci.com cat. no. - Product - Customer Drw sheet 2 of 2	

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